Docket No.: JCLA19779

Form 1595 (Rev. 09/04) RECORDATION FORM O	COVER SHEET U. S. Department of Commerce
Patent and Trademark Office PATENTS ONLY	
Name of conveying party(ies) with the execution date:	2. Name/address of receiving Party(ies)
	(1). ChipMOS Technolgies (Shanghai) Ltd.
YAN-YI WU, July 26, 2006 XIN-MING LI, July 27, 2006	9688 SONGZE AVE., QINGPU INDUSTRIAL ZONE, SHANGHAI, CHINA
CHIH-LUNG HUANG, July 27, 2006	
	(2). ChipMOS Technologies (Bermuda) Ltd.
Nature of conveyance:	CANON'S COURT, 22 VICTORIA STREET, HAMILTON HM12, BERMUDA
X Assignment Security Agreement	
Merger Change of Name Reassignment Other	
	Add'1 names of receiving parties
4. Application number(s) or patent number(s):	Attached? Yes X No
,,,,,,,,,,,,,,,,	
A. Patent Application No. (s)	B. Patent No.(s)
11/468,600	
Additional number attached?	Yes x No
5. Name and address of party to whom	Total No. of applications and patents involved:
correspondence concerning document should be mailed:	involved.
Should be mailed.	ONE (1)
J. C. Patents	7. Total fee(37CFR§3.41): \$ 40.00 Authorized to be charged by credit card
4 Venture, Suite 250	x Authorized to be charge to deposit account
Irvine, CA 92618	Enclosed
(949) 660-0761	None required (government interest not affecting title)
	8. Payment Information
	a. Credit Card Last 4 Numbers Expiration Date
	b. Deposit Account Number 50-0710
Atty Docket No.: JCLA19779	Authorized User Name <u>Jiawei Huang</u>
Statement and Signature:	
To the best of my knowledge and belief, the forging information is true and	
Correct and any attached copy is a	true copy of the original document.
Jiawei Huang	8/30/2006 Total number of pages including cover sheet, attachments, and
Name of person Signing Signature Registration No. 43,330	Date attachments, and documents: 3

PATENT

REEL: 018199 FRAME: 0733

CN-9503001 19779-US-PA

ASSIGNMENT

WHEREAS, 1. Yan-Yi Wu

2. Xin-Mina Li

3. Chih-Lung Huang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP PACKAGE STRUCTURE

[X] Filed: AUGUST 30, 2006

Serial No. 11/468,600

[] Executed concurrently with the execution of this instrument

WHEREAS, ChipMOS TECHNOLOGIES(SHANGHAI) LTD.

of 9688 Songze Ave., Qingpu Industrial Zone, Shanghai, China ChipMOS Technologies (Bermuda) Ltd.

of Canon's Court, 22 Victoria Street, Hamilton HM12, Bermuda

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Yan - Yi Wu

Date: 2006/07/26

Sole or First Joint Inventor: Yan-Yi Wu

Signature: Jin-Ming 4

Date: 20-67-27

Second Joint Inventor (if any): Xin-Ming Li

Signature: W.h. - W.q. 'Idwo'
Third Joint Inventor (if any): Chin-Lung Huang

Date: 017 619 156